2SK2015

Silicon N-Channel Power F-MOS

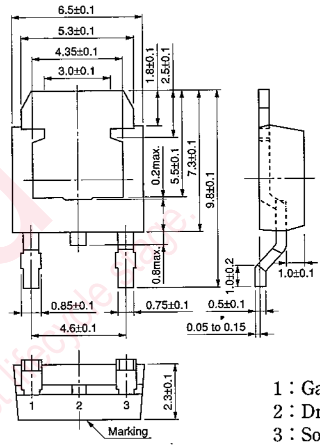
■ Features

- Low ON-resistance $R_{DS(on)}$: $R_{DS(on)}1=0.7\Omega$ (typ)
- High-speed switching : $t_f=36$ns (typ)
- No secondary breakdown
- For low-voltage drive ($V_{GS}=4$V)
- Taping supply possible

■ Applications

- DC-DC converter
- Non-contact relay
- Solenoid drive
- Motor drive

Unit : mm



1 : Gate
2 : Drain
3 : Source
EIAJ : SC-63
U Type Package

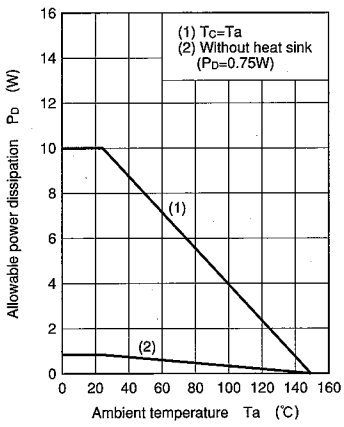
■ Absolute Maximum Ratings ($T_C=25$℃)

Parameter		Symbol	Rating	Unit
Drain-Source breakdown voltage		V_{DSS}	150	V
Gate-Source voltage		V_{GSS}	±20	V
Drain current	at 4V drive	I_D	±3	A
	Pulse	I_{DP}	±6	A
Allowable power dissipation	$T_C=25$℃	P_D	10	W
	$T_a=25$℃		0.75	
Channel temperature		T_{ch}	150	℃
Storage temperature		T_{stg}	−55 to +150	℃

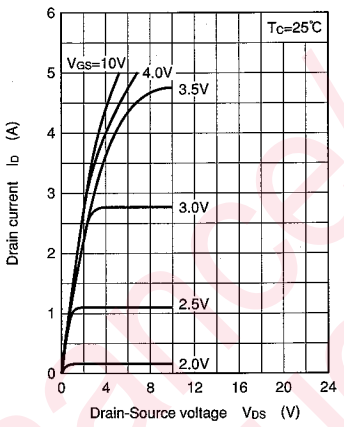
■ Electrical Characteristics ($T_C=25$℃)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Drain-Source cut-off current	I_{DSS}	$V_{DS}=130$V, $V_{GS}=0$			10	μA
Gate-Source leakage current	I_{GSS}	$V_{GS}=\pm20$V, $V_{DS}=0$			±1	μA
Drain-Source breakdown voltage	V_{DSS}	$I_D=1$mA, $V_{GS}=0$	150			V
Gate threshold voltage	V_{th}	$V_{DS}=10$V, $I_D=1$mA	1		2.5	V
Drain-Source ON-resistance	$R_{DS(on)}1$	$V_{GS}=10$V, $I_D=2$A		0.7	1.1	Ω
	$R_{DS(on)}2$	$V_{GS}=4$V, $I_D=2$A		0.8	1.3	Ω
Forward transadmittance	$\|Y_{fs}\|$	$V_{DS}=10$V, $I_D=2$A, f=1MHz	2	3.4		S
Input capacitance	C_{iss}	$V_{DS}=10$V, $V_{GS}=0$, f=1MHz		428		pF
Output capacitance	C_{oss}			97		pF
Feedback capacitance	C_{rss}			22		pF
Turn-on time	t_{on}	$V_{GS}=10$V, $I_D=2$A $V_{DD}=100$V, $R_L=50\Omega$		24		ns
Fall time	t_f			36		ns
Turn-off time (delay time)	$t_{d(off)}$			96		ns

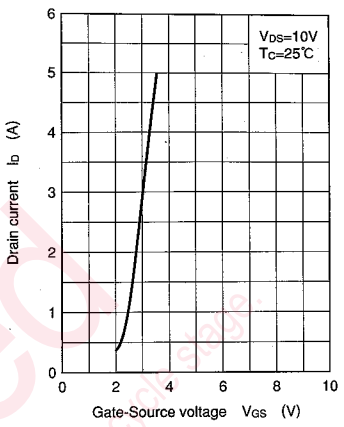
$P_D - Ta$



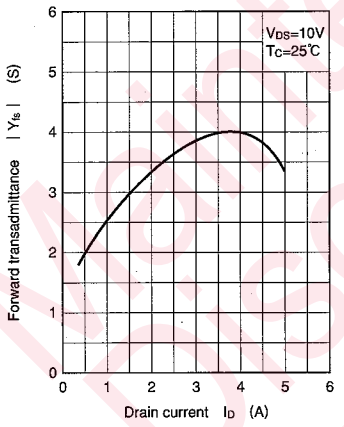
$I_D - V_{DS}$



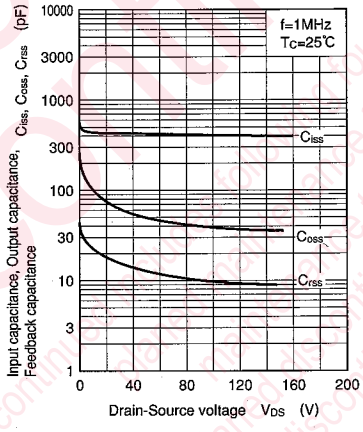
$I_D - V_{GS}$



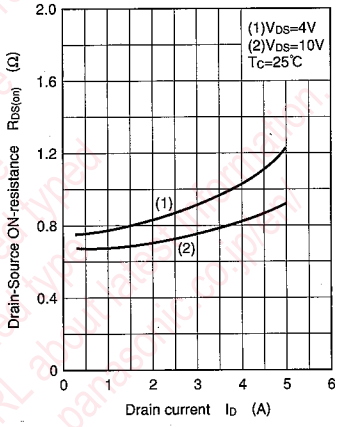
$|Y_{fs}| - I_D$



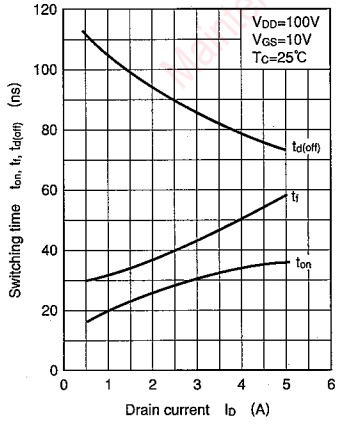
$C_{iss},\ C_{oss},\ C_{rss} - V_{DS}$



$R_{DS(on)} - I_D$



$t_{on},\ t_f,\ t_{d(off)} - I_D$



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